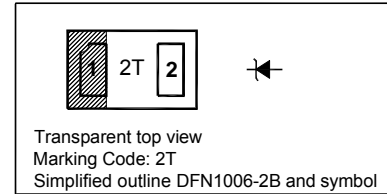


ESD9P12BP

Unidirectional ESD Protection Diode

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
IEC61000-4-2 (ESD) Contact	V_{ESD}	± 30	KV
Peak Pulse Power ($t_p = 8/20 \mu\text{s}$)	P_{PK}	140	W
Power Dissipation on FR-5 Board ¹⁾	P_{D}	150	mW
Junction Temperature	T_j	- 55 to + 150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^\circ\text{C}$

¹⁾ FR-5 = 1.0 x 0.75 x 0.62 in

Characteristics at $T_a = 25^\circ\text{C}$ ($V_F = 0.9 \text{ V Max. at } I_F = 10 \text{ mA}$)

Parameter	Symbol	Min.	Max.	Unit
Reverse Stand-Off Voltage	V_{RWM}	-	12	V
Reverse Breakdown Voltage at $I_{\text{R}} = 1 \text{ mA}$	$V_{(\text{BR})\text{R}}$	13.5	-	V
Forward Voltage at $I_F = 10 \text{ mA}$	V_F	-	1.2	V
Reverse Current at $V_{\text{RWM}} = 12 \text{ V}$	I_{R}	-	1	μA
Clamping Voltage at $I_{\text{PP}} = 5.9 \text{ A}$, $t_p = 8/20 \mu\text{s}$	V_{C}	-	23.7	V
Junction Capacitance at $V_{\text{R}} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C_j	-	30	pF

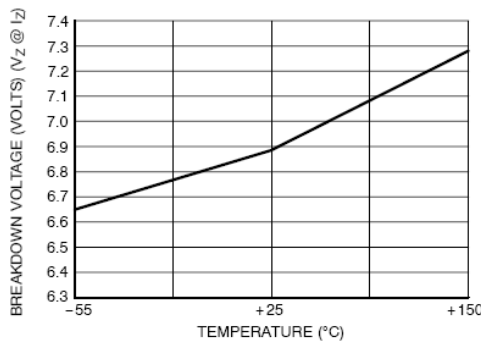


Figure 1. Typical Breakdown Voltage versus Temperature

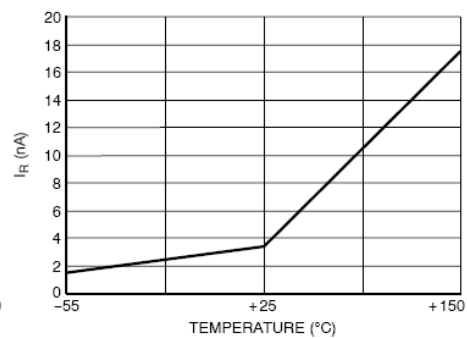


Figure 2. Typical Leakage Current versus Temperature

TOP DYNAMIC



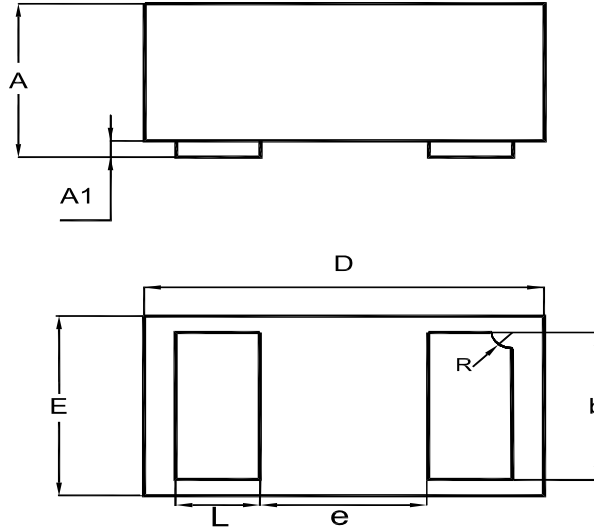
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ESD9P12BP

PACKAGE OUTLINE

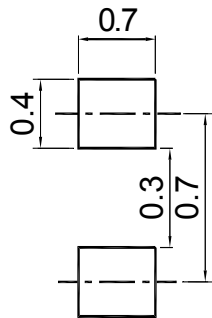
Plastic surface mounted package;

DFN1006-2B



UNIT	A	A1	b	D	E	e	L	R
mm	0.40 0.36	0.05 0	0.55 0.45	1.05 0.95	0.65 0.55	0.4	0.3 0.2	0.15 0.05

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-2B	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

TOP DYNAMIC



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